

**ELECTRONIC COMPONENTS AND SEMICONDUCTOR WAFER, AND
METHOD FOR PRODUCING THE SAME**

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Abstract

The invention relates to an electronic component and a semiconductor wafer, and a method for producing them. The semiconductor wafer has strip-type separating regions. The separating regions are provided with through contacts in the direction of the rear side of the semiconductor wafer. The semiconductor chip
10 separated from such a semiconductor wafer constitutes an electronic component with external contacts in the form of edge contacts. Such an electronic component of semiconductor chip size can be used in diverse ways.